

MOSFETs Silicon P-Channel MOS (U-MOSVI)

TPCP8110

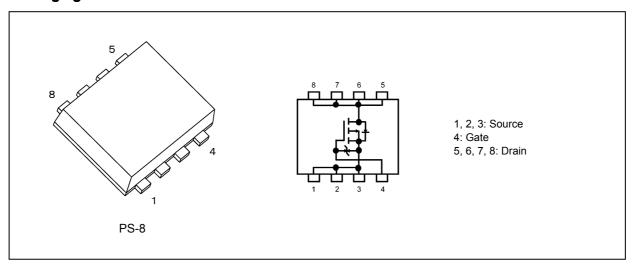
1. Applications

- · Motor Drivers
- · Mobile Equipment

2. Features

- (1) Small, thin package
- (2) Small gate charge: $Q_{SW} = 14 \text{ nC (typ.)}$
- (3) Low drain-source on-resistance: $R_{DS(ON)} = 30.4 \text{ m}\Omega$ (typ.) ($V_{GS} = -10 \text{ V}$)
- (4) Low leakage current: $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -60 \text{ V)}$
- (5) Enhancement mode: V_{th} = -2 to -3 V (V_{DS} = -10 V, I_D = -1 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (T_a = 25°C unless otherwise specified)

Characte	Symbol	Rating	Unit		
Drain-source voltage			V_{DSS}	-60	V
Gate-source voltage			V _{GSS}	-20/+10	1
Drain current (DC)		(Note 1)	I _D	-5	Α
Drain current (pulsed)		(Note 1)	I _{DP}	-20	
Power dissipation	(t = 5 s)	(Note 2)	P _D	2.01	W
Power dissipation	(t = 5 s)	(Note 3)	P_{D}	1	W
Single-pulse avalanche energy		(Note 4)	E _{AS}	101.4	mJ
Avalanche current			I _{AR}	-5	Α
Channel temperature		(Note 5)	T _{ch}	175	°C
Storage temperature			T _{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production



5. Thermal Characteristics

Characteristics			Symbol	Max	Unit
Channel-to-ambient thermal resistance	(t = 5 s)	(Note 2)	R _{th(ch-a)}	74.6	°C/W
Channel-to-ambient thermal resistance	(t = 5 s)	(Note 3)	R _{th(ch-a)}	150	

Note 1: Ensure that the channel temperature does not exceed 175°C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: V_{DD} = -25 V, T_{ch} = 25°C (initial), L = 5.512 mH, R_G = 25 Ω , I_{AR} = -5 A

Note 5: Merely Channel temperature is guaranteed 175°C.

Storage temperature range is guaranteed as usual (-55 to 150°C).

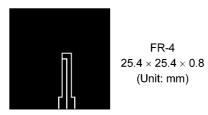


Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

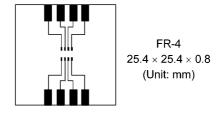


Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V _{GS} = -16/+10 V, V _{DS} = 0 V	_	_	±10	μА
Drain cut-off current	I _{DSS}	V _{DS} = -60 V, V _{GS} = 0 V	_	_	-10	
Drain-source breakdown voltage	V _{(BR)DSS}	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-60	_	1	٧
Drain-source breakdown voltage (Note 6)	V _{(BR)DSX}	I _D = -10 mA, V _{GS} = 10 V	-50	_		
Gate threshold voltage	V_{th}	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-2	-2.5	-3	
Drain-source on-resistance	R _{DS(ON)}	$V_{GS} = -6 \text{ V}, I_D = -2.5 \text{ A}$	_	33.3	53.2	mΩ
		V _{GS} = -10 V, I _D = -2.5 A	_	30.4	39.5	

Note 6: If a reverse bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	2075	_	pF
Reverse transfer capacitance	C _{rss}		_	150	_	
Output capacitance	C _{oss}		_	205	_	
Switching time (rise time)	t _r	See Figure 6.2.1.	_	9	_	ns
Switching time (turn-on time)	t _{on}		_	26	_	
Switching time (fall time)	t _f		_	27	_	
Switching time (turn-off time)	t _{off}		_	143	_	

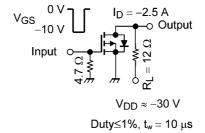


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx -48 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -5 \text{ A}$	1	45	ı	nC
Gate-source charge 1	Q _{gs1}			6		
Gate-drain charge	Q_{gd}			13		
Gate switch charge	Q_{SW}		_	14		

6.4. Source-Drain Characteristics (T_a = 25°C unless otherwise specified)

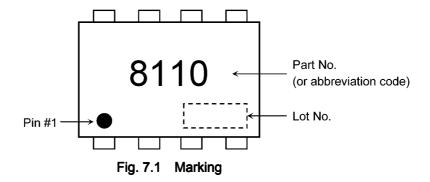
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note 7)	I _{DRP}	_	_	_	-20	Α
Diode forward voltage		V_{DSF}	I _{DR} = -5 A, V _{GS} = 0 V			1.2	V

Note 7: Ensure that the channel temperature does not exceed 175°C.

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7. Marking



8. Characteristics Curves (Note)

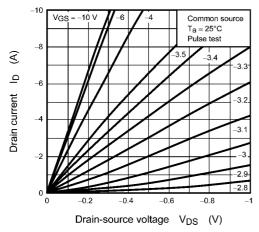
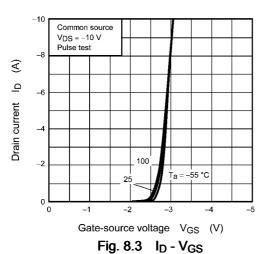


Fig. 8.1 I_D - V_{DS}



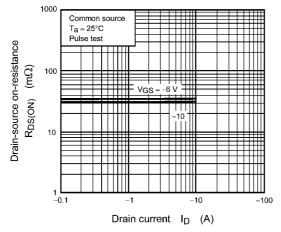


Fig. 8.5 R_{DS(ON)} - I_D

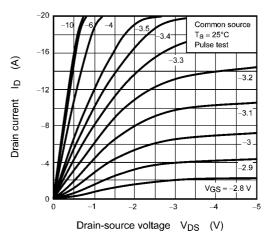


Fig. 8.2 I_D - V_{DS}

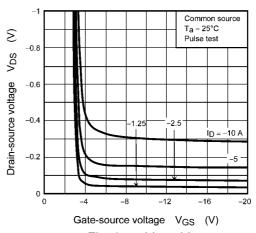


Fig. 8.4 V_{DS} - V_{GS}

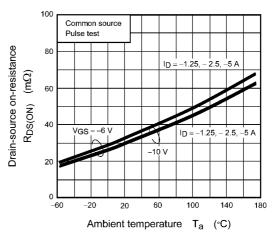


Fig. 8.6 R_{DS(ON)} - T_a (Note 8)

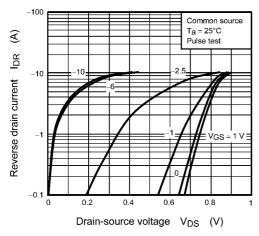


Fig. 8.7 IDR - VDS

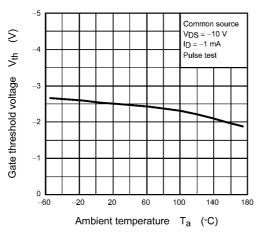
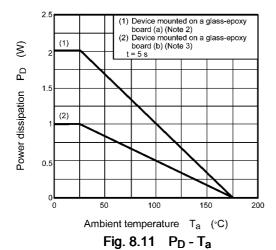


Fig. 8.9 V_{th} - T_a (Note 8)



(Guaranteed Maximum) (Note 8)

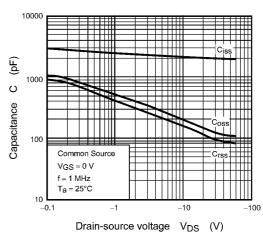


Fig. 8.8 Capacitance - V_{DS}

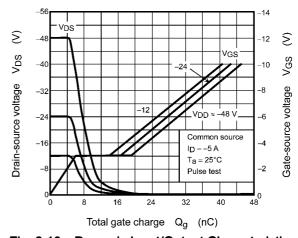


Fig. 8.10 Dynamic Input/Output Characteristics

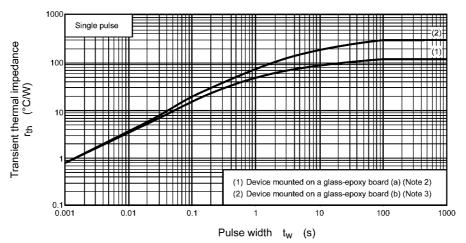


Fig. 8.12 r_{th} - t_w (Guaranteed Maximum)

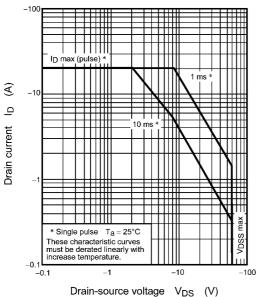


Fig. 8.13 Safe Operating Area (Guaranteed Maximum)

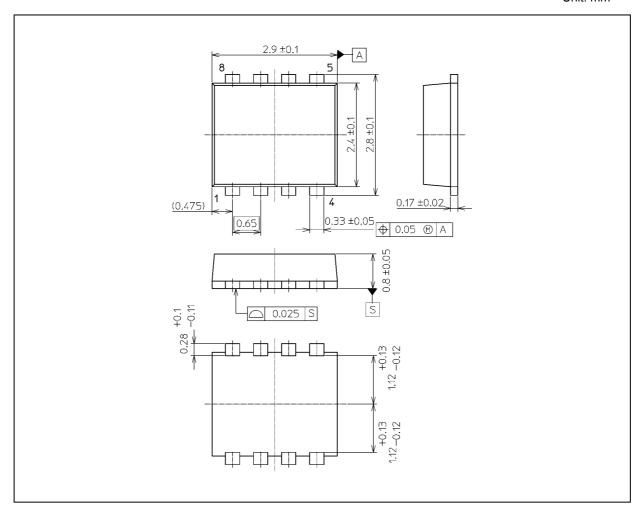
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Note 8: Although several performance curves are shown up to a T_a = 175°C, the device is not guaranteed at storage temperatures up to 175°C. The storage temperature (T_{stg}) range is rated at -55°C to 150°C.



Package Dimensions

Unit: mm



Weight: 0.017 g (typ.)

	Package Name(s)
TOSHIBA: 2-3V1S	
Nickname: PS-8	



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